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Uri Cohen, Applicant

June 21, 2006

Date of Signature

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Uri Cohen Confirmation No. 2289  
Serial No.: 10/688,333 Filed: 10/17/2003  
Grp. Art Unit: 1742 Examiner: Wilkins III, Harry D.  
Title of Application: Method and Apparatus for Activating Openings for Jets Plating

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

S I R:

**Information Disclosure Statement under 37 CFR 1.98**

Applicant respectfully requests that the reference listed on the attached form PTO-1449 be considered in the examination of the above-identified application. The listing on the form PTO-1449 shall not be construed as a representation that this reference is prior art or that no other art than that identified exists. Copies of 4 references (non-US Patents) and a check for \$180 for the IDS Fee are enclosed herein.

Respectfully submitted,

Dated: June 21, 2006

By

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PTO/SB/08 (10-92)  
Sheet 1 of 1.

<b>FORM PTO-1449</b> <b>INFORMATION DISCLOSURE CITATION</b> <b>IN AN APPLICATION</b> (Use several sheets if necessary)	<b>Docket Number (Optional):</b> JETS-02	<b>Application Number:</b> 10/688,333
	<b>Applicant:</b> Uri Cohen	<b>Examiner:</b> Wilkins III, Harry D.
	<b>Filing Date:</b> 10/17/2003	<b>Group Art Unit:</b> 1742

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	4 3 0 4 6 4 1	12/1981	Grandia et al.	205	96	
	4 7 7 1 1 1 1	09/1988	Tieke et al.	525	182	
	6 0 8 0 2 9 1	06/27/00	Woodruff et al.	204	297.01	
	6 1 7 6 9 9 2	01/23/01	Talieh	205	87	
	6 1 7 9 9 8 3	01/30/01	Reid et al.	205	96	
	6 2 2 8 2 3 2	05/08/01	Woodruff et al.	204	242	
	6 4 3 2 8 2 1	08/2002	Dubin et al.	438	678	
	6 5 3 4 1 1 6	03/2003	Basol	427	97	
US-2002/ Appl. Publ.	0 0 0 0 3 8 3	01/2002	Lee, Kevin J.	205	122	
US-2002/ Appl. Publ.	0 0 2 0 6 2 1	02/2002	Uzoh et al.	204	212	

**FOREIGN PATENT DOCUMENTS**

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES NO

**NON-PATENT LITERATURE DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)**

1	"Damascene Copper Electroplating for Chip Interconnections" by P. C. Andricacos et al., in IBM Journal of Res. and Develop., Vol. 42, No. 5, Sept. 1998, pp. 567-574
2	"Copper On-Chip Interconnections" by P. C. Andricacos in the Electrochemical Society INTERFACE, pp. 32-37, Spring 1999.
3	"Factors Influencing Damascene Feature Fill Using Copper PVD and Electroplating" by J. Reid et al., in Journal of Solid State Technology, Vol. 43(7), pp. 86-103, July 2000.
4	"Superconformal Electrodeposition of Copper in 500-90 nm Features" by T. P. Moffat et al, in Journal of The Electrochemical Society, Vol. 147(12), pp. 4524-4535, December 2000.
5	
6	

<b>EXAMINER</b>	<b>DATE CONSIDERED</b>
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**EXAMINER:** Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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